

NON-PROVISIONAL APPLICATION FOR U. S. PATENT UNDER 37 CFR 1.53(b) TRANSMITTAL FORM

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1/10 on the date shown above and is ant Commissioner for Patents,

Attorney Docket No. TI-31794

Assistant Commissioner for Patents Washington, D. C. 20231

Sir:

Transmitted herewith for filing is the patent application of:

Inventor(s): Anthony L. Coyle
Milton L. Buschbom

For:

FLIP-CHIP ON FILM ASSEMBLY FOR BALL GRID ARRAY PACKAGES.

Enclosed are:

2 Sheets of formal drawings and 24 pages of Specification (including Abstract)

X A Declaration/Power of Attorney
X Assignment with form PTO 1595

Please amend the specification by inserting before the first line the sentence: This application claims priority under 35 USC § 119 based upon **Provisional Patent Application number 60/249,385**, filed <u>11/16/00</u>.

FEE CALCULATION					FEE
	NUMBER		NUMBER EXTRA	RATE	BASIC FEE \$ 740.00
Total Claims	16	-20 =	0	X \$18 =	\$0.00
Independent Claims	3	- 3 =	0	X \$84 =	\$0.00
Total Filing Fee					\$740.00

Please charge **Deposit Account No. 20-0668** in the amount of the Total Fees set forth. The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No. 20-0668. **This form is submitted in triplicate.**

All correspondence related to this application may be addressed to the undersigned at Godwin Gruber, P.C. 801 E. Campbell Rd. Suite 655, Richardson, TX 75081.

Date: November 9, 2001

Gary J. Honeycutt

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November 9, 2001

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VIA EXPRESS MAIL

EL9297PPP9302

Assistant Commissioner for Patents Washington, D.C. 20231

Re:

Patent Application For:

FLIP-CHIP ON FILM ASSEMBLY FOR BALL GRID ARRAY PACKAGES

Attorney Docket No. TI-31794

Our File: 50000.2162

Dear Sir:

Enclosed for filing please find the following items relating to the above-identified application:

- (1) Non-Provisional Application/Fee Authorization/transmittal Form;
- (2) Declaration, and Power of Attorney;
- (3) Recordation Form Cover Sheet with Assignment;
- (4) Specifications and Formal Drawings; and
- (5) Postcards.

Please charge **Deposit Account No. 20-0668** in the amount of the total fees set forth. The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to **Deposit Account No. 20-0668**.

Please file the application and return the date-stamped postcard to the corresponding addresses as indicated. In the meantime, if you have any questions or comments concerning this matter, please call the undersigned. Otherwise, please accept the enclosed.

Sincerely,

Reg. No. 20,250

GCH/ecc

Encls.

Cc: Lawrence Bassuk, Texas Instruments Incorporated